Why attention is pay to Wafer Edge?

Particle source
Deposition film pile up at the edge when a process step goes unstable. The particle source can be identified.

Wafer crack
Wafer crack is a problem with 300 mm wafer. Scratch at edge could cause this problem.

JEOL Provides
“Wafer Edge SEM Review” Solution

The JWS (DRT) • JFS (FIB/SEM) series of tools can do wafer edge review

- JWS • JFS series high tilt, rotation stage makes edge review flexible.
- With 60° tilt* complete wafer edge can be reviewed to a point below the Apex of the Bevel.
- Possible to review the whole wafer edge with 360° endless rotation.
- Edge particle analysis is possible by EDS.

Review range at tilt 60°

Review range at 360° rotation

* for JWS-3000, max tilt angle is 45°
Example for wafer edge review

**W-CMP Wafer**

With SEM Wafer Edge Review, edge defects details can be obtained. By using EDS, it is possible to analyze components and feedback to the process for yield improvement.

**Convenient function for wafer edge review**

**Linkage with edge inspection tool**

Linkage with edge inspection tool by Raytex. Edge defect analysis can be done with high throughput.

**Auto Edge Review Function**

Automatically take whole edge continuous SEM image. Confirm defect and position.

**This function works for the following models**

- JWS-2000
- JWS-7855S
- JWS-8755S
- JWS-3000
- JFS-9200
- JFS-9300

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